

Electrostatic Discharged Protection Devices (ESD) Data Sheet

Description

Brightking's SET23C05L02 transient voltage suppressor (TVS) is designed to protect components which are connected to data and transmission lines from voltage surges caused by electrostatic discharge (ESD), electrical fast transients (EFT) and lightning.

TVS diodes are characterized by their high surge capability, low operating and clamping voltages, and fast response time. This makes them ideal for use as board level protection of sensitive semiconductor components.

The low profile SOT-23 package allows flexibility in the design of crowded circuit boards.

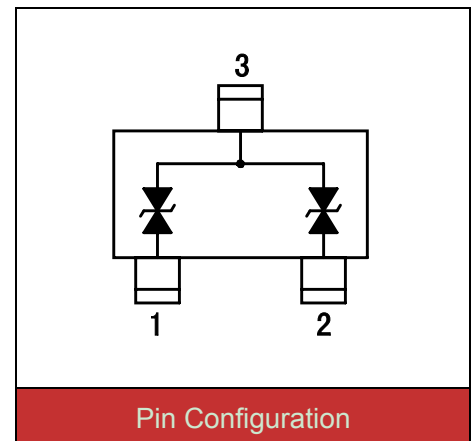


Contact : $\pm 8\text{kV}$
Air : $\pm 15\text{kV}$



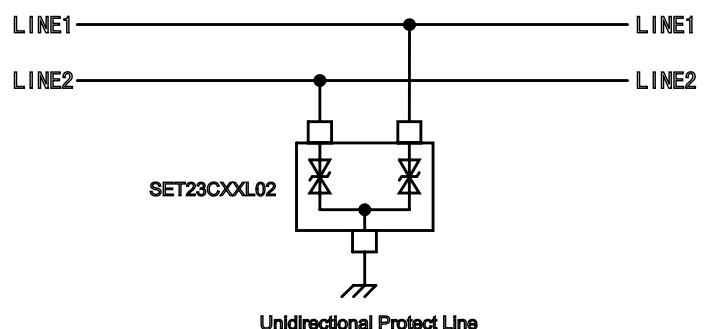
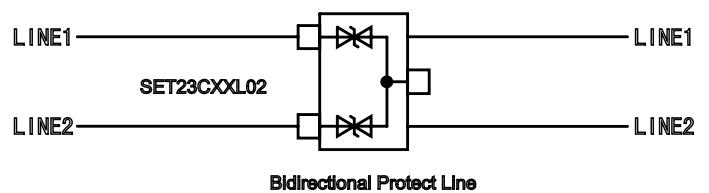
Features

- IEC61000-4-2 ESD 30KV Air, 30KV contact compliance
- SOT-23 surface mount package
- Protects one bidirectional line or two unidirectional lines
- Working voltage: 5V
- Low leakage current
- Low operating and clamping voltages
- Solid-state silicon avalanche technology
- Lead Free/RoHS compliant
- Solder reflow temperature: Pure Tin-Sn, 260~270°C
- Flammability rating UL 94V-0
- Meets MSL level 1, per J-STD-020
- Marking: B 05C



Applications

- Cellular handsets and accessories
- Personal digital assistants (PDA's)
- Portable instrumentation
- Set Top Box (STB)
- Servers, notebook, and desktop PC
- Wireless bus protection
- RS-232, RS-422, RS-423 protection



Maximum Ratings

| Rating | Symbol | Value | Unit |
|---------------------------------------|----------------|----------|-------------|
| ESD voltage (Contact discharge) | V_{ESD} | ± 30 | kV |
| ESD voltage (Air discharge) | | ± 30 | |
| Storage & operating temperature range | T_{STG}, T_J | -55~+150 | $^{\circ}C$ |

Electrical Characteristics ($T_J=25^{\circ}C$)

| Parameter | Symbol | Condition | Min. | Typ. | Max. | Unit |
|--------------------------------------|-----------|--|------|------|------|---------|
| Reverse stand-off voltage | V_{RWM} | | | | 5 | V |
| Reverse breakdown voltage | V_{BR} | $I_{BR}=1mA$ | 5.2 | | | V |
| Reverse leakage current | I_R | $V_R=5V$ Each I/O pin | | | 5 | μA |
| Clamping voltage ($t_p=8/20\mu s$) | V_C | $I_{PP}=1A$ | | | 9.8 | V |
| Clamping voltage ($t_p=8/20\mu s$) | V_C | $I_{PP}=30A$ | | | 18 | V |
| Off state junction capacitance | C_J | 0Vdc, f=1MHz Between I/O pins and GND | | 80 | | pF |

Typical Characteristics Curves

Figure 1. Power Derating Curve

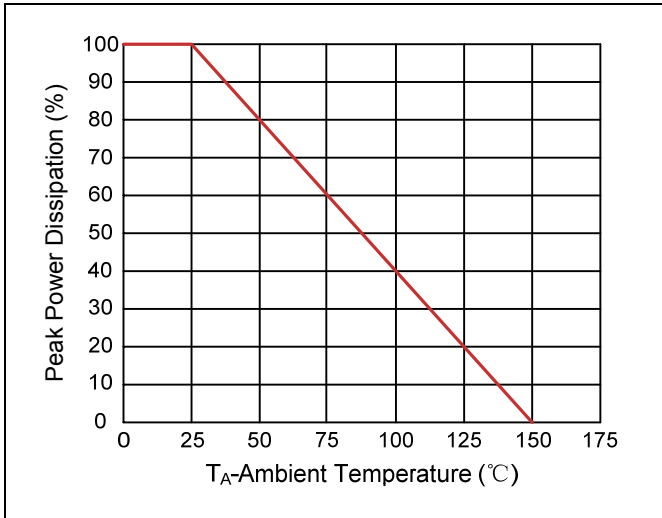


Figure 2. Pulse Waveforms

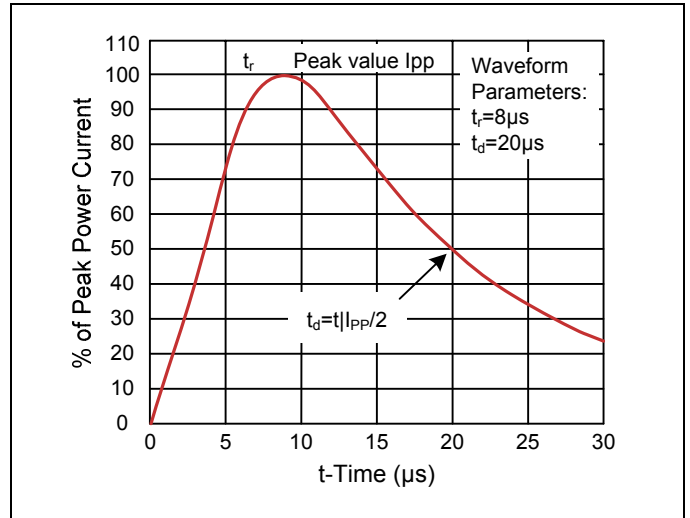


Figure 3. Clamping Voltage vs. Peak Pulse Current

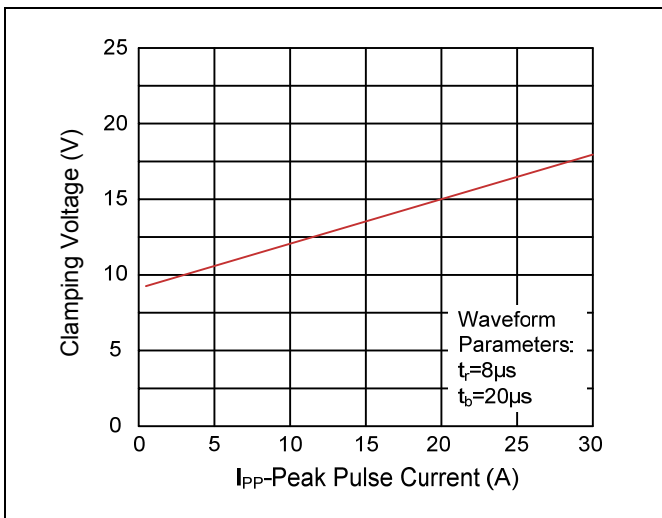
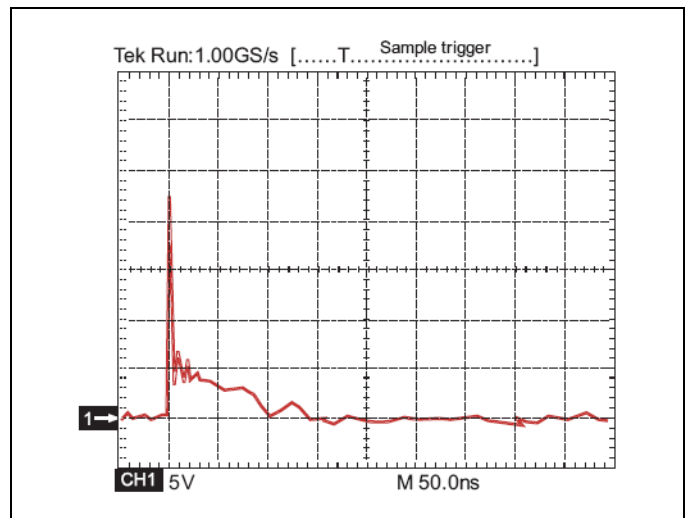
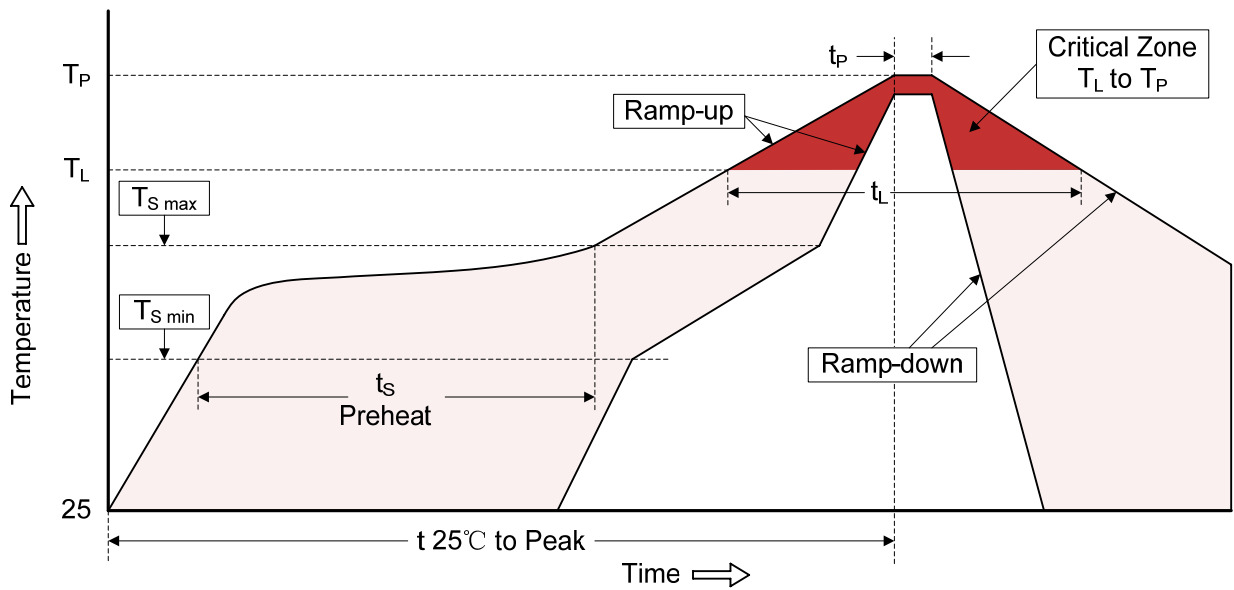


Figure 4. ESD Clamping(8kV Contact IEC61000-4-2)



Recommended Soldering Conditions

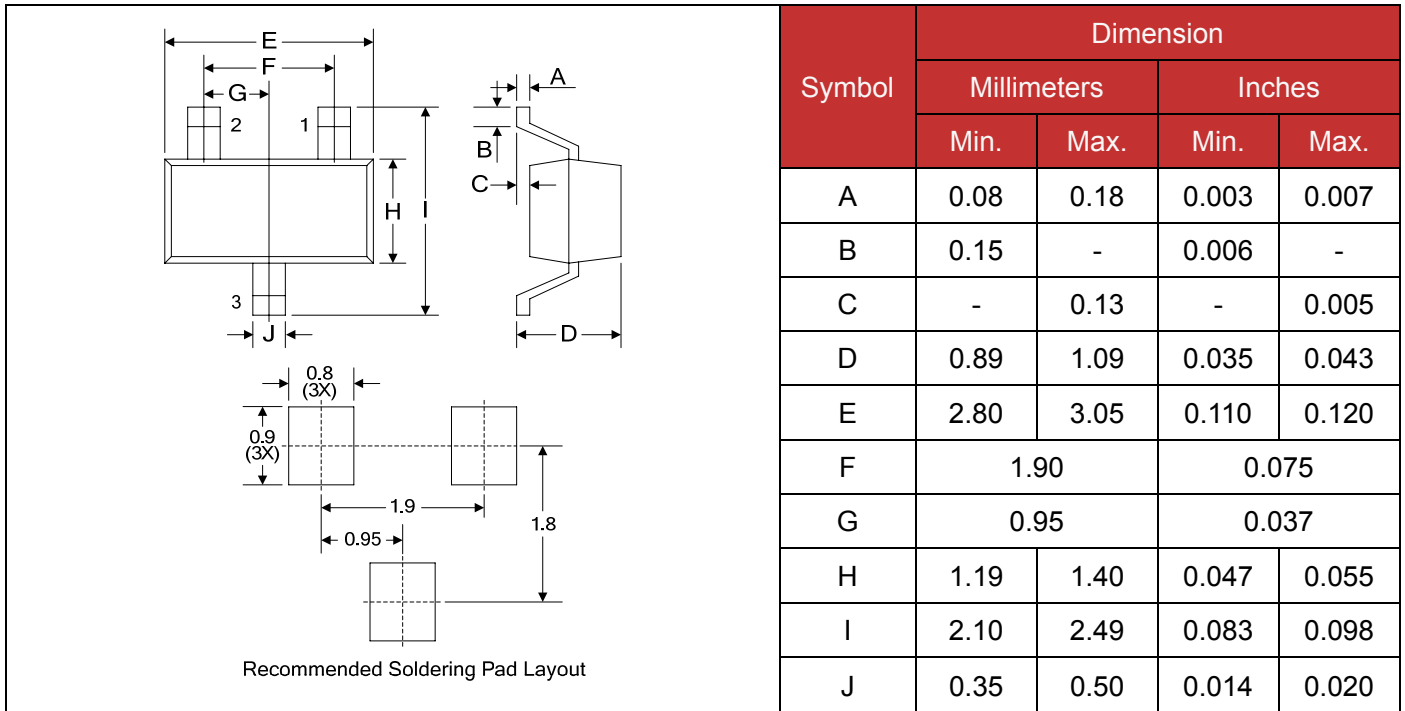
Reflow Soldering



Recommended Conditions

| Profile Feature | Pb-Free Assembly |
|---|----------------------------------|
| Average ramp-up rate (T_L to T_P) | 3°C/second max. |
| Preheat -Temperature Min ($T_{S\ min}$) -Temperature Max ($T_{S\ max}$) -Time (min to max) (t_s) | 150°C 200°C 60-180 seconds |
| $T_{S\ max}$ to T_L -Ramp-up Rate | 3°C/second max. |
| Time maintained above: -Temperature (T_L) -Time (t_L) | 217°C 60-150 seconds |
| Peak Temperature (T_P) | 260°C |
| Time within 5°C of actual Peak Temperature (t_p) | 20-40 seconds |
| Ramp-down Rate | 6°C/second max. |
| Time 25°C to Peak Temperature | 8 minutes max. |

Dimensions (SOT-23)



Packaging

